IIRW
IEEE
INTERNATIONAL INTEGRATED RELIABILITY WORKSHOP

October 8-12, 2023

Stanford Sierra Conference Center Fallen Leaf Lake, CA, USA

Abstract Deadline
July 16, 2023

Author Notification
August 13, 2023

Late News Deadline
September 10, 2023

General Chair:
Francesco Maria Puglisi
University of Modena and Reggio Emilia

TPC Chair:
Charles LaRow
Intel Corporation

www.iirw.org

The **IEEE International Integrated Reliability Workshop (IIRW)** focuses on ensuring electronic device reliability through fabrication, design, testing, characterization, and simulation, as well as identification of the defects and physical mechanisms responsible for reliability problems.

IIRW 2023:

- Best Student Paper Award
- All accepted papers published in IEEEXplore
- Top 5-7 papers will be extended for publication in IEEE TDMR
- Reliability Experts Forum: Discussion with several panelists among the top reliability experts from industry, research centers, and academia on the current understanding and challenges of hot topics in reliability.

Outstanding features of the IIRW are:

- Strong plenary, invited, tutorials, and technical program
- Unparalleled opportunities to meet world-leading experts
- Discussion and special interest groups sessions
- Unique rustic and secluded environment

IIRW 2023 welcomes abstracts on, but not limited to, these topics:

- **FOCUS AREA:** Circuit reliability, device-circuit degradation, aging
- **FOCUS AREA:** Advanced node scaling solutions (FEOL/MOL/BEOL)
- **FOCUS AREA:** Machine learning for reliability
- **FOCUS AREA:** Multi-die chip Packaging
- In-memory computing and neuromorphic reliability
- Plasma-induced damage (PID), electrostatic discharge (ESD), Failure analysis
- FEOL/MOL/BEOL dielectrics (high-k, SiO_2, SiON, low-k)
- FET, FinFET, SOI, III-V, SiGe reliability (HCI, BTI, TDDB, RTN, etc.)
- Conventional and emerging memories (Flash, RRAM, Ferroelectrics, etc.)
- Emerging technologies and devices (2D materials, IGZO, etc.)
- Power, wide-bandgap (SiC, GaN, etc.) devices and circuits reliability
- RF and mm/sub-mm Wave devices and circuits reliability
- Modeling and simulation for reliability, including self-heating
- Process integration and advanced packaging reliability
- Design-in-reliability (products, circuits, systems, processes)
- Reliability of advanced automotive circuits, systems, products
- Customer/manufacturer product reliability requirements
- Wafer-level reliability tests for monitoring and qualification

Two-page abstract with representative data and figures should clearly state the results of your work and why they are significant.

For more information, please visit www.iirw.org, or contact:
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